

# L2N7002SLLT1G S-L2N7002SLLT1G

Small Signal MOSFET 380 mAmps, 60V N–Channel SOT-23

### 1. FEATURES

- We declare that the material of product compliance with RoHS requirements and Halogen Free.
- S- prefix for automotive and other applications requiring unique site and control change requirements; AEC-Q101 qualified and PPAP capable.
- ESD protected
- Low RDS(on)

### 2. APPLICATIONS

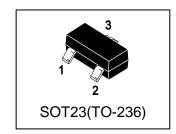
- Low side load switch
- · Level shift circuits
- DC-DC converter
- Portable applications i.e. DSC, PDA, Cell Phone, etc.

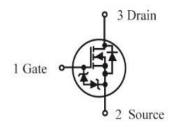
### 3. DEVICE MARKING AND ORDERING INFORMATION

Device	Marking	Shipping
L2N7002SLLT1G	701	3000/Tape&Reel
L2N7002SLLT3G	701	10000/Tape&Reel

#### 4. MAXIMUM RATINGS(Ta = 25°C)

	Parameter	Symbol	Limits	Unit
Drain-Source	e Voltage	VDSS	60	V
Gate-Source	Voltage	VGS	±20	V
Drain Curren	t	ID		mΑ
<ul><li>Steady Sta</li></ul>	te TA = 25°C		320	
	$TA = 85^{\circ}C$		230	
– t<5s	$TA = 25^{\circ}C$		380	
	$TA = 85^{\circ}C$		270	
Pulsed Drain	Current (tp=10µs)	IDM	1.5	Α
Source Curre	ent (Body Diode)	IS	300	mA







### 5. THERMAL CHARACTERISTICS

Parameter	Symbol	Limits	Unit
Total Device Dissipation(Note 1)	PD		mW
<ul><li>Steady State</li></ul>		300	
– t<5s		420	
Junction-to-Ambient(Note 1)	RΘJA		°C/W
<ul><li>Steady State</li></ul>		417	
– t<5s		300	
Lead Temperature for Soldering Purposes (1/8 " from case for 10 s)	TL	260	°C
Junction and Storage temperature	TJ,Tstg	-55~+150	°C
Gate-Source ESD Rating(HBM, Method 3015)	ESD	2000	V

# 6. ELECTRICAL CHARACTERISTICS (Ta= 25°C)

### OFF CHARACTERISTICS

Characteristic		Symbol	Min.	Тур.	Max.	Unit
Drain–Source Breakdown Voltage		VBRDSS				V
(VGS = 0, ID = 250μA)			60	-	-	
Drain-to-Source Breakdown Voltage	e	VBRDSS/TJ				mV/° C
Temperature Coefficient		V D ( D 0 0 / 1 0	-	71	-	
Zero Gate Voltage Drain Current	TJ = 25°C		-		1.0	μA
(VGS = 0, VDS = 60 V)	TJ = 125°C	IDSS			500	
(VGS = 0, VDS = 50 V)	$TJ = 25^{\circ}C$		ı	1	100	nA
Gate–Body Leakage Current, Forward		IGSSF				μΑ
(VGS = 20 V)		10001	-	1	10	
Gate–Body Leakage Current, Reverse		IGSSR				μΑ
(VGS = - 20 V)		IGGGN	-	-	-10	

### ON CHARACTERISTICS (Note 2)

Gate Threshold Voltage	VGS(th)				V
(VDS = VGS, ID = 250μA)	VG3(III)	1.0	-	2.0	
Negative Threshold Temperature Coefficient	VGS(TH)/TJ	-	4	-	mV/° C
Static Drain–Source On–State Resistance	RDS(on)				Ω
(VGS = 10 V, ID = 500 mA)		-	-	2.8	
(VGS = 4.5 V, ID = 200 mA)		-	-	3.2	
Forward Transconductance	gfs				mS
(VDS = 5.0 V, ID = 200 mA)	gis	80	-	-	

### DYNAMIC CHARACTERISTICS

Input Capacitance		Ciss				pF
(VDS = 25 V, VGS = 0, f =	= 1.0 MHz)	CISS	-	-	35	
Output Capacitance		Coss				pF
(VDS = 25 V, VGS = 0, f =	= 1.0 MHz)	C055	-	-	10	
Reverse Transfer Capacitance		Crss				pF
(VDS = 25 V, VGS = 0, f =	= 1.0 MHz)	Clas	-	-	5	
Total Gate Charge	VCC 45V VDC 40	QG(TOT)	1	0.44	1	nC
Gate-to-Source Charge	VGS = 4.5 V, VDS = 10 V; ID= 500 mA	QGS	1	0.2	1	
Gate-to-Drain Charge	V, 1D= 000 111/1	QGD	1	0.1	1	
Gate Resistance (VDS = 0 V,VGS = 0 V,f =	: 1.0 MHz)	Rg	-	30	-	ΚΩ



**Small Signal MOSFET** 

# 6. ELECTRICAL CHARACTERISTICS (Ta= 25°C)(Con.)

### SWITCHING CHARACTERISTICS

Turn-On Delay Time	\/DQ	td(on)	1	20	1	ns
Rise Time	VDS = 30 V, VGEN = 10 V, ID = 500 mA,RG =25Ω ,RL	tr	-	55	-	
Turn-Off Delay Time	=60Ω	td(off)	-	200	-	
Fall Time		tf	-	180	-	

### **BODY-DRAIN DIODE RATINGS**

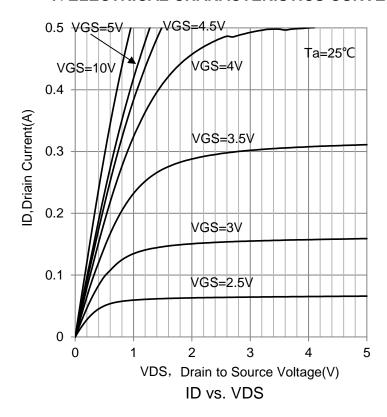
Diode Forward On–Voltage	VSD				V
(IS = 0.5A, VGS = 0 V)	V3D	-	0.85	-	

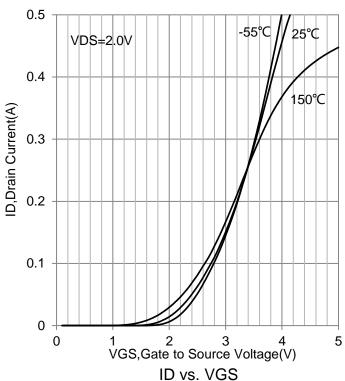
<sup>1.</sup>  $FR-4 = 1.0 \times 0.75 \times 0.062$  in.

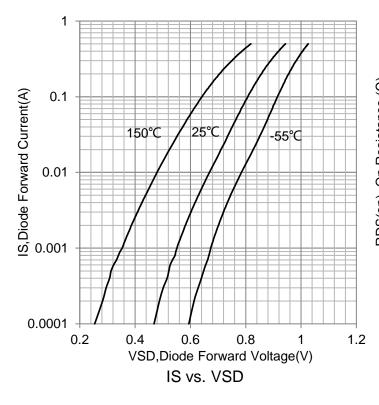
<sup>2.</sup>Pulse Test: Pulse Width  $\leq$ 300 µs, Duty Cycle  $\leq$ 2.0%.

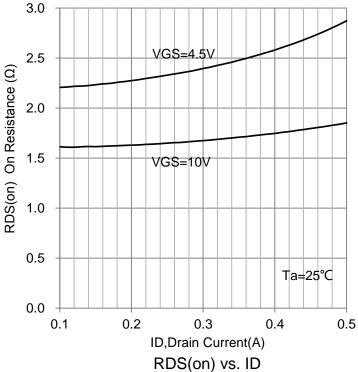


### 7. ELECTRICAL CHARACTERISTICS CURVES



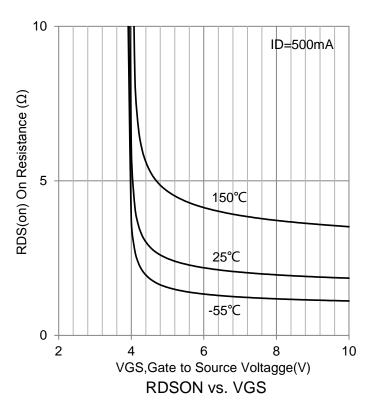


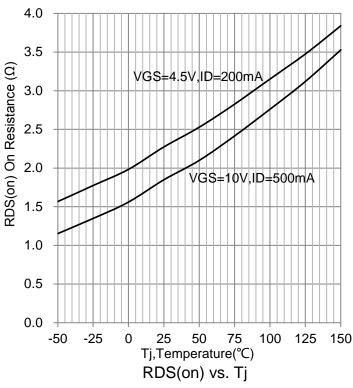


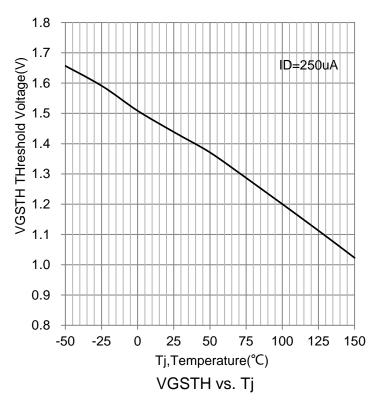


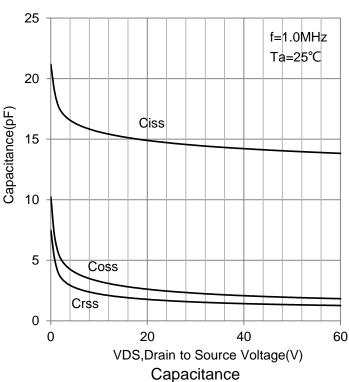


### 7. ELECTRICAL CHARACTERISTICS CURVES(Con.)









MAX

0.044

0.004

0.02

0.007

0.12

0.055

0.081

0.012

0.029

0.104

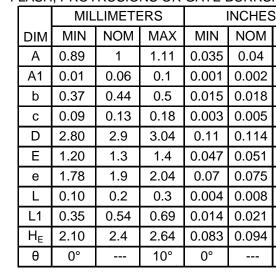
10°

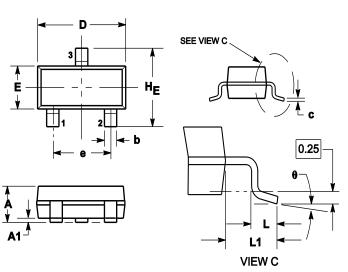


#### 8.OUTLINE AND DIMENSIONS

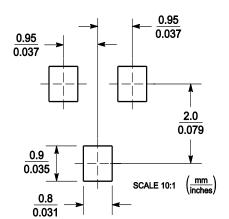
#### Notes:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETERS.
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- 4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.





### 9.SOLDERING FOOTPRINT





### **DISCLAIMER**

- Curve guarantee in the specification. The curve of test items with electric parameter is used as quality guarantee. The curve of test items without electric parameter is used as reference only.
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